



Solder **plus** Support

**PRESS RELEASE:**  
FOR IMMEDIATE RELEASE

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## AIM's David Solis to Present at SMTA Juarez Technical Seminar

**March 11<sup>th</sup>, 2019 — Cranston, Rhode Island USA** – AIM Solder, a leading global manufacturer of solder assembly materials for the electronics industry, is pleased to announce that David Solis will present at the 2019 SMTA Juarez Technical Seminar at Four Centuries Convention Center in Cd Juarez, Chihuahua, Mexico. David's presentation, "Assessing the Effectiveness of IO Stencil Aperture Modifications on BTC Void Reduction," will be presented in two parts on March 14, 2019. Part one of the presentation is at 6:30 PM and part two is at 7:20 PM.

Mr. Solis will present the results of an AIM study examining the effect of QFN I/O paste deposits on ground pad voiding. BTCs have been rapidly incorporated into PCB designs because of their low cost, small footprint and overall reliability. The combination of leadless terminations and ground/thermal pads create a number of challenges, including tilting, poor solder fillet formation, difficult inspection and – most notably – center/ground pad voiding. Voids in ground pad solder joints can be difficult to control due to the variety of input variables that can influence their formation. Most of the published center pad voiding studies have focused on optimizing center pad footprint and stencil aperture designs. This study focuses on I/O pad stencil modifications rather than center pad modifications. It shows a no-cost, easily implemented I/O design guideline that can be deployed to consistently and repeatedly reduce void formation on BTC-style packages.

To discover all of AIM's products and services, visit [www.aimsolder.com](http://www.aimsolder.com).

### **About the Presenter**

David Solis is a Technical Application Engineer with over 20 years of experience in the electronics industry, specializing in SMT maintenance and production for automotive, commercial, medical and solar industries. A Selective Solder Process Expert, with additional certifications in Bullet Proof management and Process Optimization, he also has experience as a manufacturing and project engineer.

### **About AIM**

Headquartered in Montreal, Canada, AIM Solder is a leading global manufacturer of assembly materials for the electronics industry with manufacturing, distribution and support facilities located throughout the world. AIM produces advanced solder products such as solder paste, liquid flux, cored wire, bar solder, epoxies, lead-free and halogen-free solder products, and specialty alloys such as indium and gold for a broad range of industries. A recipient of many prestigious SMT industry awards, AIM is strongly committed to innovative research and development of product and process improvement as well as providing customers with superior technical support, service and training. For more information about AIM, visit [www.aimsolder.com](http://www.aimsolder.com).



David Solis  
Technical Support Engineer, AIM





**Upcoming Events:**

March 20-22, 2019 – Productronica China, Shanghai, China

March 26, 2019 – SMTA Intermountain, Boise State University, Boise, ID

April 4, 2019 – SMTA Chihuahua, Chihuahua, Mexico